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(54) **INTERCONNECT DEVICE AND METHOD**

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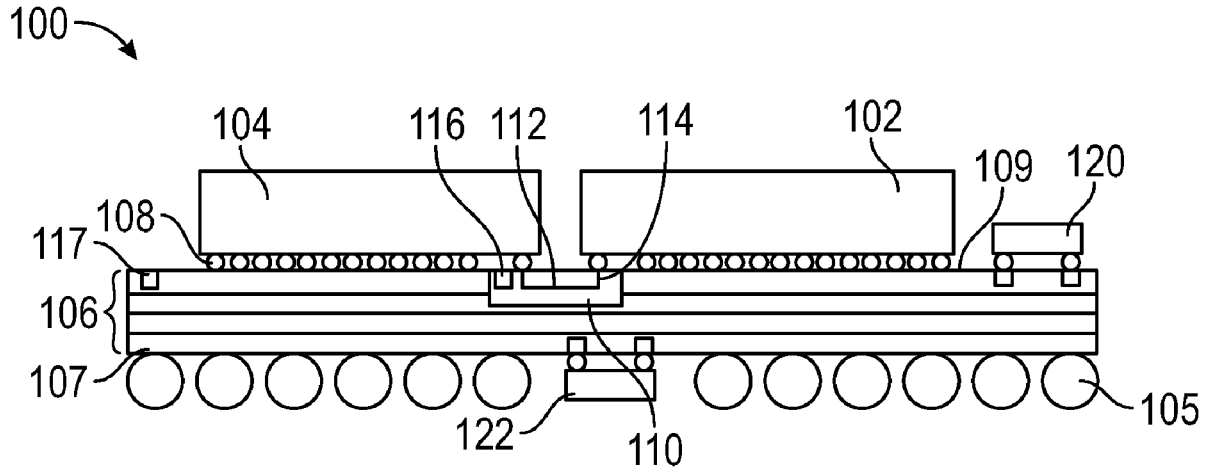
(57) **ABSTRACT**

An electronic device and associated methods are disclosed. In one example, the electronic device includes vertical connections with a layer including tin between the vertical connections and conductive traces. In selected examples, a layer including tin is used in conjunction with other interface layers. In selected examples, a layer including tin is used in all vertical connections.